



ISTFA/2018 FAILURES WORTH ANALYZING

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General Chair

LatticeGear



Dr. Felix Beaudoin
Vice General Chair

GLOBALFOUNDRIES



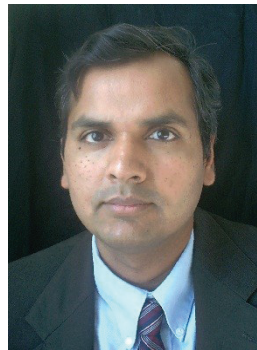
Dr. David Grosjean
Technical Program Chair

Butterfly Networks, Inc.



Dr. Mayue Xie
Tutorial & Short Course
Chair

Intel



Dr. Sam Subramanian
Immediate Past General Chair
NXP Semiconductors

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ISTFA 2018 TECHNICAL PROGRAM COMMITTEE



ISTFA 2018 Technical Program Chair

Dr. David Grosjean
Butterfly Networks, Inc.

Session Chairs

3D Device Failure Analysis

Christian Schmidt, *NVIDIA*
Jesse Alton, *TeraView LTD*

Board and System Level FA

Jason Wheeler, *Raytheon*
Becky Holdford, *Texas Instruments*

Detecting and Preventing Counterfeit Microelectronics

Michael D. Woo, *Raytheon*
Michael H. Azarian, *CALCE, University of Maryland*

Emerging FA Techniques and Concepts

Dan Bodoh, *NXP Semiconductors*
Frank Altmann, *Fraunhofer Institute for Mechanics of Materials*

FA Processes Case Studies

Erwin Hendarto, *Silicon Labs*
Chuan Zhang, *GLOBALFOUNDRIES*

Fault Isolation

Keith A. Serrels, *NXP Semiconductors*
Joe Caroselli, *AMD*

FIB Circuit Analysis and Edit

Ken Lagarec, *Fibics Incorporated*
Shida Tan, *Intel*

FIB Sample Preparation

Bryan Tracy, *Evans Analytical Group*
Antonio Tollis, *Analog Devices*

Hardware Attacks, Security, and Reverse Engineering

Domenic Forte, *University of Florida*
Ujjwal Guin, *Auburn University*

Low Power Devices and Test Structures Case Studies

Michael Bruce, *Consultant*
Rose Ring, *LAM Research*

Microscopy

Lianfeng Fu, *Lam Research Corporation*
Edgar Voelkl, *Consultant*

Mixed Mode & High Power Devices Case Studies

Stephen T. Fasolino, *Raytheon*
Jared Eisenhower, *Medtronic*

Nanoprobng and Electrical Characterization

Sweta Pendyala, *GLOBALFOUNDRIES*
John Sanders, *Thermo Fisher Scientific*

Packaging & Assembly Level FA

Peng Li, *Intel Corporation*
Kannu Wadhwa, *ZEISS*

Product Yield, Test & Diagnostics

Jayant Dsouza, *Mentor, A Siemens Business*
Amit M. Jakati, *GLOBALFOUNDRIES*

Sample Preparation and Device Deprocessing

Ryan Fredrickson, *On Semiconductor*
Hueihao Yap, *GLOBALFOUNDRIES*

Scanning Probe Analysis

Phil Kaszuba, *GLOBALFOUNDRIES*
Paiboon Tangyunyong, *Sandia National Laboratories*

Space Application FA

Ted Kolasa, *Orbital ATK*
Richard Blank, *California Institute of Technology*